

BAS70VV

70 V, 70 mA Schottky barrier triple isolated diode in SOT666

Rev. 01 — 10 September 2004

Product data sheet

1. Product profile

1.1 General description

Planar Schottky barrier triple diode with an integrated guard ring for stress protection. Three electrically isolated Schottky barrier diodes, encapsulated in a SOT666 ultra small SMD plastic package.

1.2 Features

- Low forward voltage
- High reverse voltage
- Low capacitance
- Ultra small SMD plastic package
- Flat leads: excellent coplanarity and improved thermal behavior.

1.3 Applications

- Ultra high-speed switching
- Voltage clamping
- Line termination
- Inverse-polarity protection
- RF applications (e.g. mixing and demodulation).

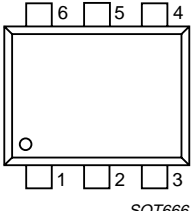
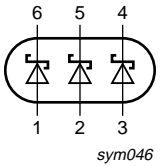
1.4 Quick reference data

Table 1: Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_R	reverse voltage		-	-	70	V
I_F	forward current		-	-	70	mA

2. Pinning information

Table 2: Discrete pinning

Pin	Description	Simplified outline	Symbol
1	anode (diode 1)	 <p style="text-align: center;">SOT666</p>	 <p style="text-align: center;">sym046</p>
2	anode (diode 2)		
3	anode (diode 3)		
4	cathode (diode 3)		
5	cathode (diode 2)		
6	cathode (diode 1)		

3. Ordering information

Table 3: Ordering information

Type number	Package		
	Name	Description	Version
BAS70VV	-	plastic surface mounted package; 6 leads	SOT666

4. Marking

Table 4: Marking

Type number	Marking code
BAS70VV	N1

5. Limiting values

Table 5: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
Per diode					
V_R	reverse voltage		-	70	V
I_F	forward current		-	70	mA
I_{FRM}	repetitive peak forward current	$t_p \leq 1 \text{ s}; \delta \leq 0.5$	-	70	mA
I_{FSM}	non-repetitive peak forward current	$t_p < 10 \text{ ms}$	-	100	mA
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-65	+150	°C
T_{stg}	storage temperature		-65	+150	°C

6. Thermal characteristics

Table 6: Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	700	K/W

[1] Refer to SOT666 standard mounting conditions.

[2] Reflow soldering is the only recommended soldering method.

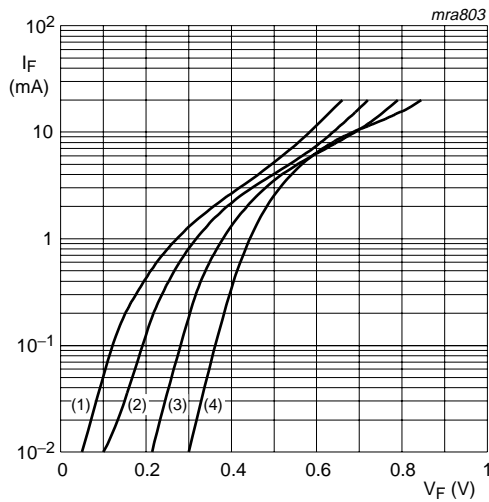
7. Characteristics

Table 7: Characteristics

$T_{amb} = 25^\circ\text{C}$ unless otherwise specified.

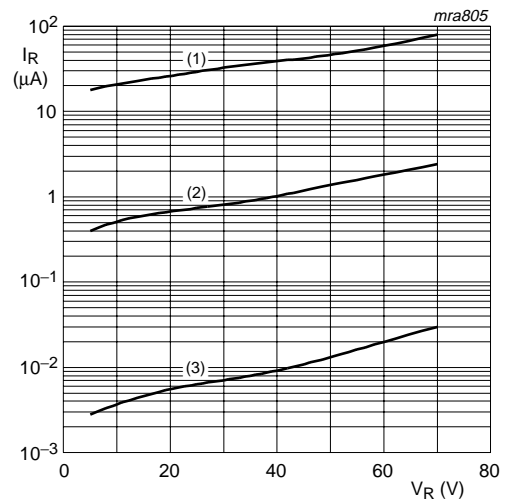
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per diode						
V_F	forward voltage	see Figure 1	[1]			
		$I_F = 1\text{ mA}$	-	-	410	mV
		$I_F = 10\text{ mA}$	-	-	750	mV
		$I_F = 15\text{ mA}$	-	-	1	V
I_R	reverse current	see Figure 2				
		$V_R = 50\text{ V}$	-	-	100	nA
		$V_R = 70\text{ V}$	-	-	10	μA
C_d	diode capacitance	$V_R = 0\text{ V}$; $f = 1\text{ MHz}$; see Figure 4	-	-	2	pF

[1] Pulse test: $t_p \leq 300\ \mu\text{s}$; $\delta \leq 0.02$.



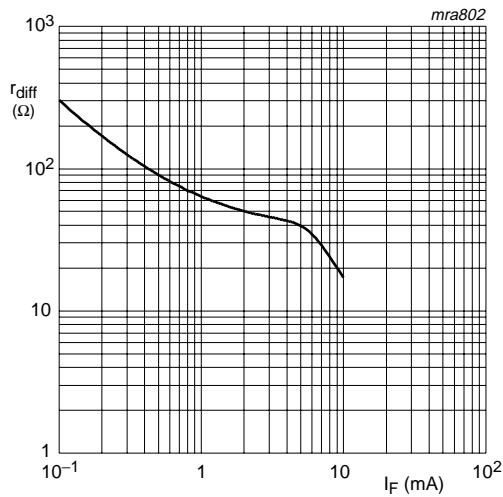
- (1) $T_{\text{amb}} = 125^\circ\text{C}$.
- (2) $T_{\text{amb}} = 85^\circ\text{C}$.
- (3) $T_{\text{amb}} = 25^\circ\text{C}$.
- (4) $T_{\text{amb}} = -40^\circ\text{C}$.

Fig 1. Forward current as a function of forward voltage; typical values.



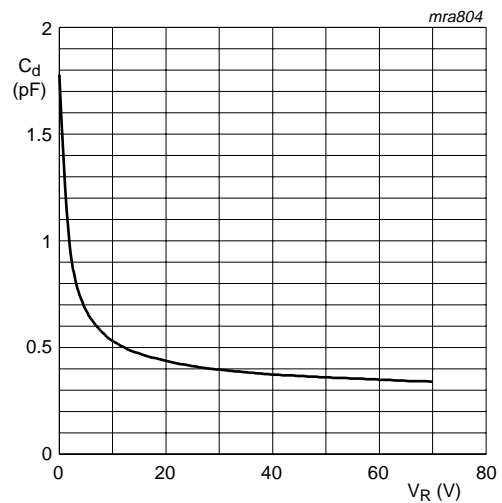
- (1) $T_{\text{amb}} = 125^\circ\text{C}$.
- (2) $T_{\text{amb}} = 85^\circ\text{C}$.
- (3) $T_{\text{amb}} = 25^\circ\text{C}$.

Fig 2. Reverse current as a function of reverse voltage; typical values.



$f = 10\ \text{kHz}$.

Fig 3. Differential forward resistance as a function of forward current; typical values.



$f = 1\ \text{MHz}$.

Fig 4. Diode capacitance as a function of reverse voltage; typical values.

8. Package outline

Plastic surface mounted package; 6 leads

SOT666

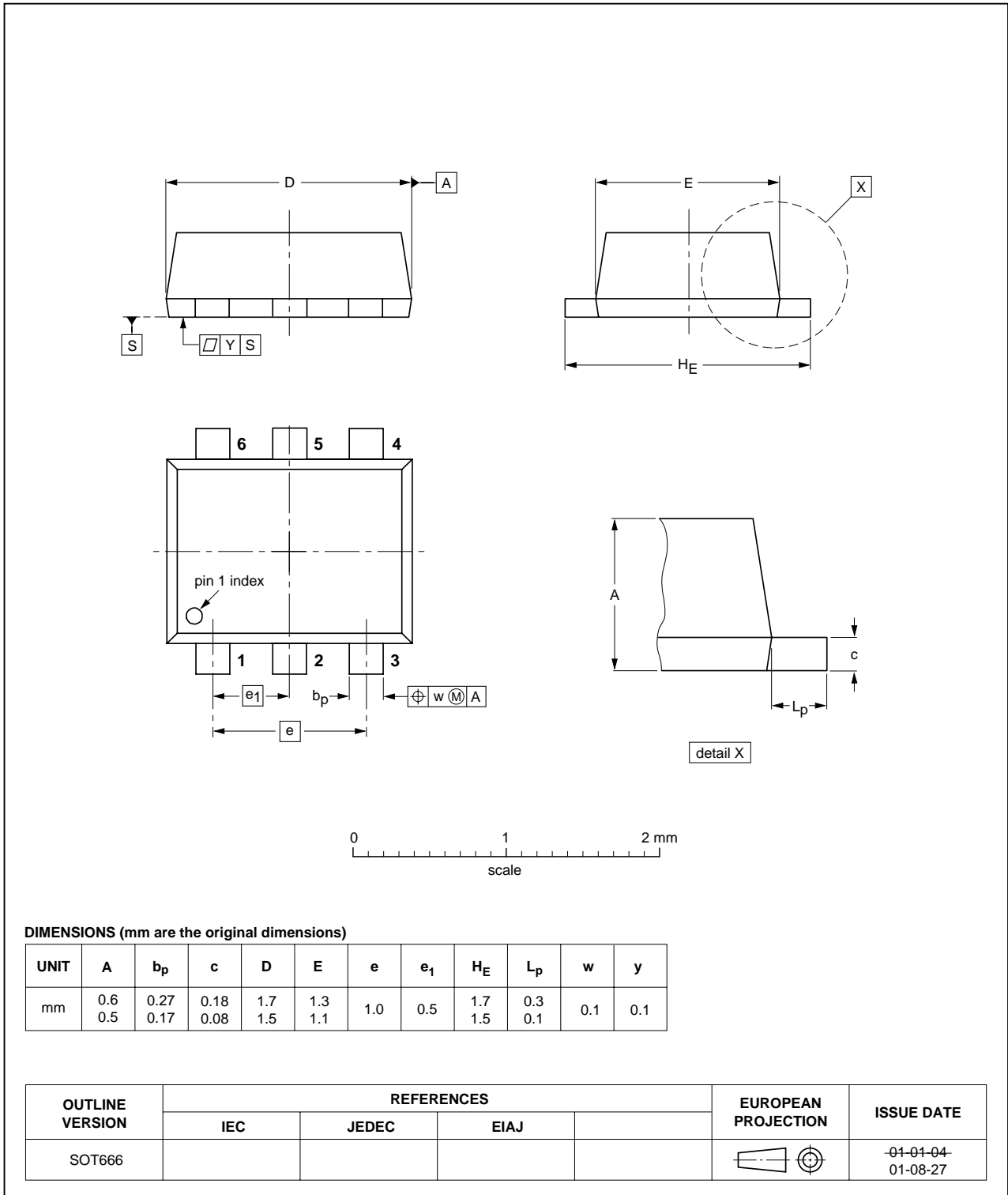


Fig 5. Package outline SOT666.

9. Packing information

Table 8: Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code^[1]

Type number	Package	Description	Packing quantity
			4000
BAS70VV	SOT666	4 mm pitch, 8 mm tape and reel	-115

[1] For further information and the availability of packing methods, see [Section 14](#).

10. Revision history

Table 9: Revision history

Document ID	Release date	Data sheet status	Change notice	Order number	Supersedes
BAS70VV_1	20040910	Product data sheet	-	9397 750 13732	-

11. Data sheet status

Level	Data sheet status ^[1]	Product status ^[2] ^[3]	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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